



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Warren M. Farnworth

**Serial No.:** 10/043,468

**Filed:** January 10, 2002

**For:** METHOD OF FORMING  
OVERMOLDED CHIP SCALE PACKAGE  
AND RESULTING PRODUCT

**Confirmation No.:** 7094

**Examiner:** K. Nguyen

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-3085.4US  
(96-1033.04/US)

**Notice of Allowance Mailed:**

January 2, 2004

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 19, 2004  
Date

Doreen Neumann  
Signature

Doreen Neumann  
Name (Type/Print)

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Abstract** appear on page 10 of this paper.

**Serial No. 10/043,468**

**Amendments to the Claims** are reflected in the listing of claims which begins on page 11 of this paper.

**Remarks** begin on page 17 of this paper.